2SK1070

Silicon N-Channel Junction FET

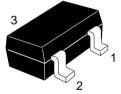
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Application

Low frequency / High frequency amplifier

Outline

MPAK



- 1. Drain
- 2. Source
- 3. Gate



2SK1070

Absolute Maximum Ratings (Ta = 25°C)

| Item | Symbol | Ratings | Unit |
|---------------------------|------------------|-------------|------|
| Gate to drain voltage | V_{GDO} | -22 | V |
| Gate to source voltage | $V_{\rm gso}$ | -22 | V |
| Drain current | I _D | 50 | mA |
| Gate current | I _G | 10 | mA |
| Channel power dissipation | Pch | 150 | mW |
| Channel temperature | Tch | 150 | °C |
| Storage temperature | Tstg | -55 to +150 | °C |

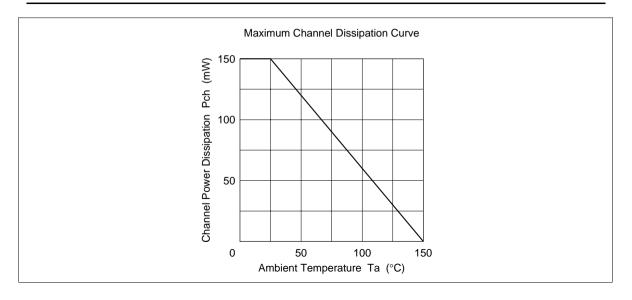
Electrical Characteristics (Ta = 25°C)

| Item | Symbol | Min | Тур | Max | Unit | Test conditions |
|----------------------------------|---------------------|-----|-----|------|------|--|
| Gate cutoff current | I _{GSS} | _ | _ | -10 | nA | $V_{GS} = -15 \text{ V}, V_{DS} = 0$ |
| Gate to source breakdown voltage | $V_{(BR)GSS}$ | -22 | _ | _ | V | $I_{G} = -10 \ \mu A, \ V_{DS} = 0$ |
| Drain current | I _{DSS} *1 | 6 | _ | 40 | mA | $V_{DS} = 5 \text{ V}, V_{GS} = 0, \text{ Pulse test}$ |
| Gate to source cutoff voltage | $V_{GS(off)}$ | 0 | _ | -2.5 | V | $V_{DS} = 5 \text{ V}, I_{D} = 10 \mu\text{A}$ |
| Forward transfer admittance | y _{fs} | 20 | 30 | _ | mS | $V_{DS} = 5 \text{ V}, V_{GS} = 0, f = 1 \text{ kHz}$ |
| Input capacitance | Ciss | _ | 9 | _ | pF | $V_{DS} = 5 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$ |

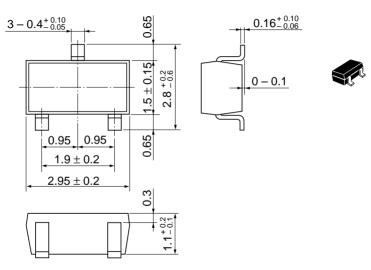
Note: 1. The 2SK1070 is grouped by I_{DSS} as follows.

| Grade | В | С | D | E | |
|------------------|---------|----------|----------|----------|--|
| Mark | PIB | PIC | PID | PIE | |
| I _{DSS} | 6 to 14 | 12 to 22 | 18 to 30 | 27 to 40 | |

See characteristic curves of 2SK435.



Unit: mm



| Hitachi Code | MPAK |
|--------------------------|----------|
| JEDEC | _ |
| EIAJ | Conforms |
| Weight (reference value) | 0.011 g |

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